

# MODEL ATM-1100G

## Full Automatic Wafer Protective Tape Laminating Machine

### Outline

The ATM-1100G is the ideal system for laminating tape to wafers, before the backgrind process.

### Features

- Special controlled cutting along the wafer contour after tape lamination ensures the production of uniform and high precision taper laminates free from bubbles.
- Special controlled cutting provides notched wafers and all-angle secondary flat positioned wafers.
- Ensures lower running cost.
- Without providing tape tension onto wafer, wafer does not have any stress after Back Grinding.



| Specification |               | ATM-1100G  |
|---------------|---------------|--|
| Throughput    |               | 90wafers/hour(Depend on data setting)              |
| Wafer Size    |               | 4.5*6.8 inch                                       |
| Tape Width    |               | 130~230mm  |
| Utilities     | Power         | AC100V 50/60Hz Single phase 1.5KVA                 |
|               | Air           | 0.5Mpa 90NI/min                                    |
|               | Vacuum source | -74Kpa   |
| Dimensions    |               | D1,140 × W1,200 × H1,645mm Excuanding signal tower |
| Weight        |               | Approx 500kg                                       |

System appearance and specifications are subject to change without prior notice from the supplier.

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